

**IN THE CLAIMS:**

Claims 1-16 (Previously canceled)

Claim 17 (Currently Amended) A method of manufacturing an integrated circuit, comprising:

forming an active device on a semiconductor wafer;

forming a substrate over the active device;

polishing the substrate with a polishing tool using a polishing slurry thereby creating a waste slurry;

conveying the waste slurry to a drain, the waste slurry forming an agglomerate in the drain and having an agglomerate particle size;

subjecting the waste slurry within the drain to ~~energy~~ an ultrasonic energy source as the waste slurry passes into or through the drain to a waste slurry recovery tank ~~emanating from an energy source~~; and

transferring energy from the ultrasonic energy source to the waste slurry to substantially reduce the agglomerate particle size within the waste slurry recovery tank.

Claim18 (Currently Amended) The method as recited in Claim 17 further comprising sensing ~~a~~ an absorbance of the waste slurry with a absorbance sensor coupled to the drain.

Claim 19 (Original) The method as recited in Claim 18 wherein the subjecting includes cycling off the subjecting when the sensing discerns a nominal absorbance or less, and cycling on the subjecting when the sensing discerns greater than the nominal absorbance.

Claim 20 (Original) The method as recited in Claim 19 wherein sensing a nominal absorbance includes sensing a nominal absorbance of less than about 0.5.

Claim 21 (Currently Canceled).

Claim 22 (Currently Canceled).

Claim 23 (Currently Canceled).

Claims 24-27 (Previously canceled)